Roll No

MEVD - 203

M.E./M.Tech., II Semester

Examination, June 2016

VLSI Test and Testability

Time: Three Hours

Maximum Marks: 70

Note: i) Attempt any five questions.

- ii) All questions carry equal marks.
- Explain IC production test process and burn-in-board.
 - Explain different levels of testing. Also discuss design for testability.
- Discuss different types of faults in VLSI circuits during fabrication and packaging.
 - Describe the transistor faults and delay faults in fault detection process.
- What is simulation? Explain parallel and detective fault simulation.
 - b) Briefly explain path sensitization method and its limitation.
- Explain the testing of sequential circuit as iterative combinational circuit.
 - List various methods for Stuck-at faults. Elaborate any one of them giving suitable example.

- Describe the testing of sequential circuits as state table verification and random testing.
 - Discuss the generic offline BIST architecture.
- Explain Ad-Hoc testable design techniques.

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- Discuss Full scan and Partial scan design.
- Discuss IDDQ testing with importance in VLSI design.
 - Explain BIST implementation in hardware design.
- Write short notes on any two
 - Controllability and observability
 - CMOS testing
 - Fault collapsing
 - Boundary scans

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